



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SOT-23					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
HAST	646	64 600	130 °C, 85 % RH	0	0
Pressure Pot	1046	100 416	121°, 15 PSIG	0	0
Solder DUNK	270	810	260 °C, 10 s	0	0
Solderability	150	870	883 M2003	0	0
Temp. Cycle	3564	1 304 000	-55 °C to 150 °C	0	0